

Data sheet

SAW duplexer LTE / 5G band 12

Part number: B1272

Ordering code: B39741B1272L210

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1 Application

- Duplexer for 4G and 5G band 12
- LTE band 12 uplink: 707.5 MHz (pass band 17 MHz)
- LTE band 12 downlink: 737.5 MHz (pass band 17 MHz)
- Qualcomm® micro-Acoustic Power Management (MAPM)
- High attenuation
- Low amplitude ripple
- Single-ended duplexer
- Very small size and low height

2 Features

- Package size 1.6±0.05 mm × 1.2±0.05 mm
- Package height 0.6 mm (max.)
- Approximate weight 3 mg
- RoHS compatible
- Package for Surface Mount Technology (SMT)
- Ni/Au-plated terminals
- Filter surface passivated
- Electrostatic Sensitive Device (ESD)
- Moisture Sensitivity Level 3 (MSL3)

3 Package

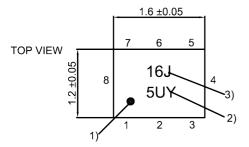
Pad and pitch tolerance ±0.05

SIDE VIEW

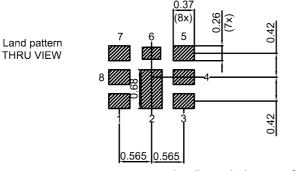


4 Pin configuration

- 1 RX
- 3 TX
- 6 ANT
- 2, 4, 5, 7, Ground 8



- 1) Marking for pad number 1
- 2) Example of encoded lot number
- 3) Example of encoded filter type number



Landing pad tolerance -0.02

Figure 1: Drawing of package with package height A = 0.6 mm (max.). See Sec. Package information (p. 22).

5 Matching circuit

■ L_{p6} = 12 nH

Europe GmbH

■ L_{s3} = 6.0 nH

■ L_{s1} = 2.0 nH

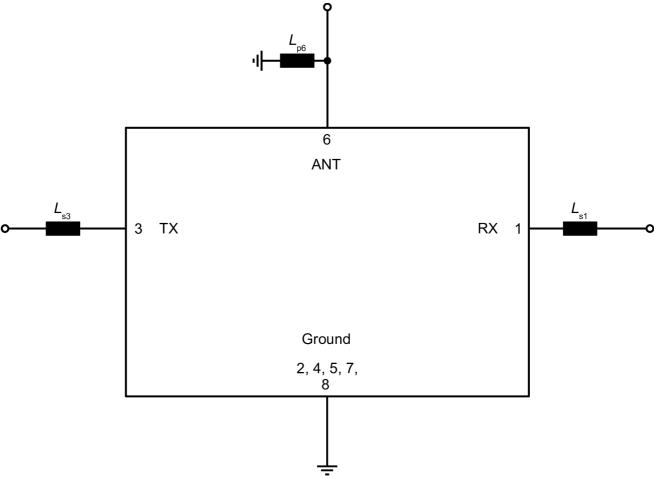


Figure 2: Schematic of matching circuit.



6 Characteristics

6.1 TX - ANT

Europe GmbH

Temperature range for specification $T_{\rm SPEC} = -30~{\rm ^{\circ}C}~...~+85~{\rm ^{\circ}C}$ TX terminating impedance $Z_{\rm TX} = 50~\Omega~+6.0~{\rm nH^{1)}}$ ANT terminating impedance $Z_{\rm ANT} = 50~\Omega~//~12~{\rm nH^{1)}}$ RX terminating impedance $Z_{\rm RX} = 50~\Omega~+2.0~{\rm nH^{1)}}$

Characteristics TX – ANT				$\begin{array}{c c} \mathbf{min.} \\ \mathbf{for} \ T_{\mathtt{SPEC}} \end{array}$	typ. @ +25 °C	$\begin{array}{c} \text{max.} \\ \text{for } T_{\text{\tiny SPEC}} \end{array}$	
Center frequency			f _C	- SPEC	707.5	— SPEC	MHz
Maximum insertion attenuation							
maximum moortion attoridation	699.24 715.76	MHz	$\boldsymbol{\alpha}_{\text{max}}$		1.4	2.1	dB
Amplitude ripple (p. p.)	099.24 715.70	IVII IZ	۸~	_	1.4	2.1	ub
Amplitude ripple (p-p)	000 04 745 70	N 41 1—	Δα		0.5	4.0	40
Marrian VOMB	699.24 715.76	MHz	VCMD	_	0.5	1.2	dB
Maximum VSWR			$VSWR_{max}$				
@ TX port	699.24 715.76	MHz		_	1.4	2.0	
@ ANT port	699.24 715.76	MHz		_	1.4	2.0	
Minimum attenuation			$\boldsymbol{\alpha}_{\text{min}}$				
	10 686	MHz		33	39	_	dB
	729 746	MHz		45	58	_	dB
	758 768	MHz		35	43	_	dB
	768 805	MHz		35	40	_	dB
	824 849	MHz		35	40	_	dB
	869 894	MHz		35	40	_	dB
	1166 1187	MHz		37	42	_	dB
	1226 1250	MHz		37	43	_	dB
	1398 1432	MHz		40	46	_	dB
	1559 1563	MHz		45	50	_	dB
	1565.42 1573.37	MHz		45	49	_	dB
	1573.37 1577.47	MHz		45	50	_	dB
	1577.47 1585.42	MHz		45	50	_	dB
	1597.55 1605.89	MHz		45	50	_	dB
	1710 1785	MHz		45	52	_	dB
	1805 1880	MHz		45	54	_	dB
	1850 1915	MHz		50	55	_	dB
	1930 1990	MHz		50	57	_	dB
	2097 2155	MHz		50	61	_	dB
	2110 2200	MHz		50	60	_	dB
	2350 2360	MHz		50	60	_	dB
	2400 2690	MHz		50	57	_	dB
	2402 2494	MHz		50	59	_	dB
	2796 2864	MHz		50	56	_	dB
	3300 3800	MHz		50	55	_	dB
	4900 5950	MHz		33	38	_	dB

See Sec. Matching circuit (p. 6).



6.2 ANT - RX

Europe GmbH

 $\begin{array}{lll} \mbox{Temperature range for specification} & T_{\rm SPEC} & = -30~{\rm ^{\circ}C}~...~+85~{\rm ^{\circ}C} \\ \mbox{TX terminating impedance} & Z_{\rm TX} & = 50~\Omega~+6.0~{\rm nH^{1)}} \\ \mbox{ANT terminating impedance} & Z_{\rm ANT} & = 50~\Omega~/~12~{\rm nH^{1)}} \\ \mbox{RX terminating impedance} & Z_{\rm RX} & = 50~\Omega~+2.0~{\rm nH^{1)}} \\ \end{array}$

Characteristics ANT – RX				$\begin{array}{c} \text{min.} \\ \text{for } T_{\text{SPEC}} \end{array}$	typ. @ +25 °C	$\begin{array}{c} \text{max.} \\ \text{for } T_{\text{SPEC}} \end{array}$	
Center frequency			f _C	_	737.5	_	MHz
Maximum insertion attenuation			$\boldsymbol{\alpha}_{\text{max}}$				
	729.24 745.76	MHz		_	1.7	2.3	dB
Amplitude ripple (p-p)			Δα				
	729.24 745.76	MHz		_	0.4	1.0	dB
Maximum VSWR			$VSWR_{max}$				
@ ANT port	729.24 745.76	MHz		_	1.4	2.0	
@ RX port	729.24 745.76	MHz		_	1.4	2.0	
Minimum attenuation			$\boldsymbol{\alpha}_{\text{min}}$				
	10 699	MHz		50	55	_	dB
	30	MHz		50	82	_	dB
	663 698	MHz		50	57	_	dB
	699 716	MHz		55	63	_	dB
	776 798	MHz		40	46	_	dB
	824 849	MHz		40	49	_	dB
	1710 1780	MHz		48	55	_	dB
	1850 1915	MHz		48	53	_	dB
	2187 2238	MHz		45	50	_	dB
	2305 2315	MHz		45	50	_	dB
	2400 2500	MHz		45	50	_	dB
	2496 2690	MHz		45	49	_	dB
	3300 3800	MHz		45	49	_	dB
	4900 5950	MHz		25	33	_	dB
	6561 6714	MHz		30	38	_	dB

¹⁾ See Sec. Matching circuit (p. 6).



6.3 TX - RX

 $\begin{array}{lll} \mbox{Temperature range for specification} & T_{\rm SPEC} & = -30~{\rm ^{\circ}C}~...~+85~{\rm ^{\circ}C} \\ \mbox{TX terminating impedance} & Z_{\rm TX} & = 50~\Omega~+6.0~{\rm nH^{1)}} \\ \mbox{ANT terminating impedance} & Z_{\rm ANT} & = 50~\Omega~/~12~{\rm nH^{1)}} \\ \mbox{RX terminating impedance} & Z_{\rm RX} & = 50~\Omega~+2.0~{\rm nH^{1)}} \\ \end{array}$

Characteristics TX – RX				$\begin{array}{c} \text{min.} \\ \text{for } T_{\text{SPEC}} \end{array}$	typ. @ +25 °C	$\begin{array}{c} \text{max.} \\ \text{for } T_{\text{SPEC}} \end{array}$	
Minimum isolation			α_{min}				
699.15 71	5.85	MHz		55	60	<u> </u>	dB
729.15 74	5.85	MHz		55	60	<u> </u>	dB

¹⁾ See Sec. Matching circuit (p. 6).



7 **Maximum ratings**

Storage temperature	$T_{\rm STG}^{1)} = -40 ^{\circ}\text{C} +85 ^{\circ}\text{C}$	
DC voltage	$ V_{DC} ^{2)} = 0 \text{ V (max.)}$	
ESD voltage		
	$V_{ESD}^{3)} = 225 \text{ V (max.)}$	Human body model.
	$V_{\rm ESD}^{4)} = 700 \text{V (max.)}$	Charged device model.
	$V_{\rm ESD}^{5)} = 125 \text{V (max.)}$	Machine model.
Input power	P _{IN}	
@ TX port: 699 716 MHz	30 dBm	Continuous wave for 5000 h @ 50 °C.
@ TX port: 699 716 MHz	30 dBm	5MHz LTE uplink signal for 5000 h @ 50 °C.
@ TX port: 699 716 MHz	28.5 dBm	5MHz 5G NR (CP-OFDM) 1RB for 5000 h @ 50 °C.
@ TX port: other frequency ranges	10 dBm	Continuous wave for 5000 h @ 50 °C.

¹⁾ Not valid for packaging material. Storage temperature for packaging material is −25 °C to +40 °C.

²⁾

In case of applied DC voltage blocking capacitors are mandatory.

According to JESD22-A114F (HBM – Human Body Model), 1 negative & 1 positive pulse. 3)

According to JESD22-C101C (CDM – Field Induced Charged Device Model), 3 negative & 3 positive pulses.

According to JESD22-A115B (MM – Machine Model), 10 negative & 10 positive pulses.



8 **Transmission coefficients**

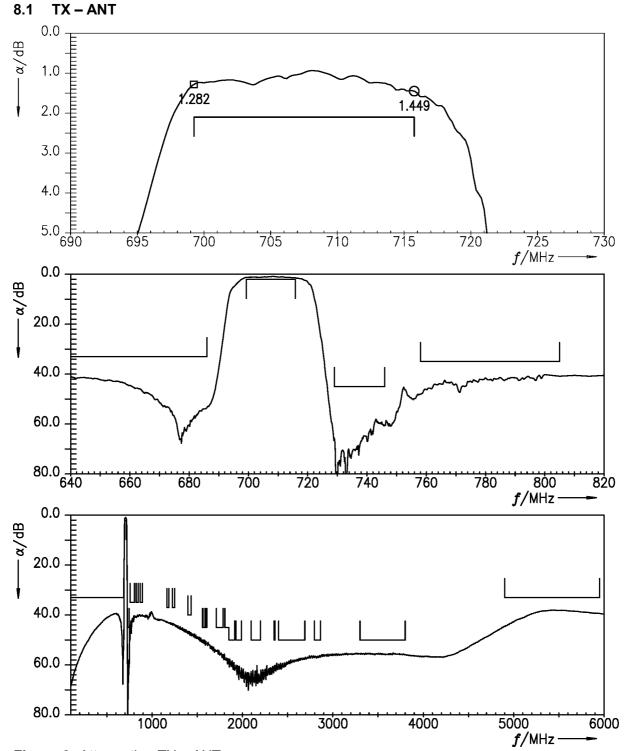


Figure 3: Attenuation TX – ANT.

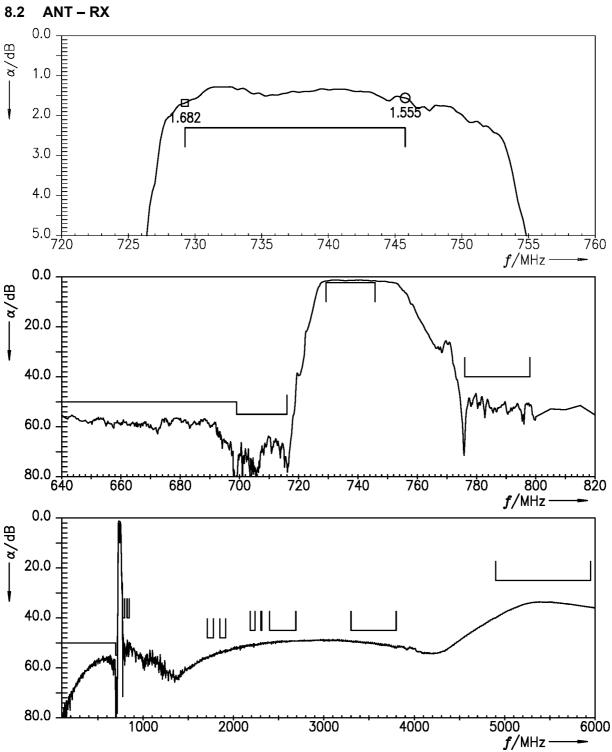


Figure 4: Attenuation ANT – RX.

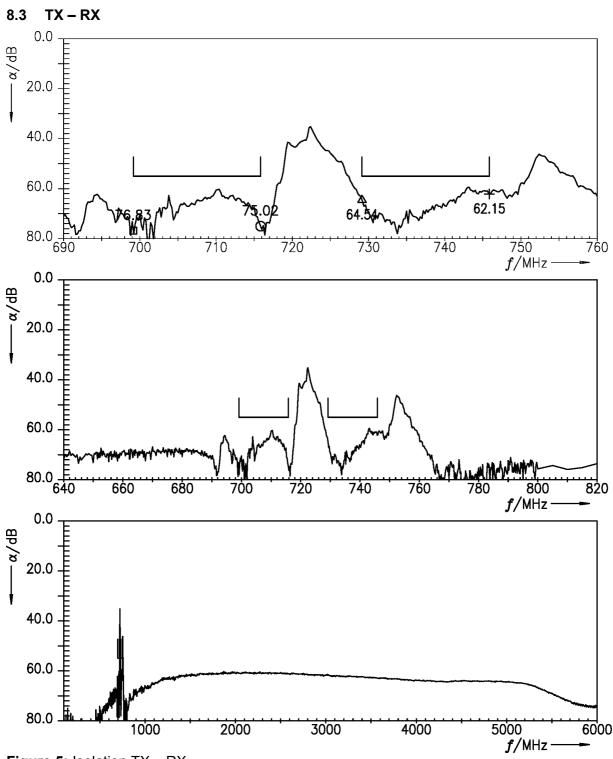
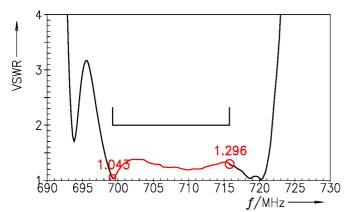
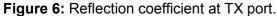
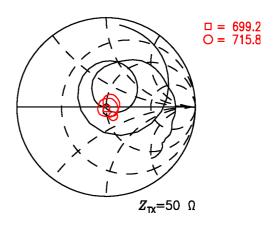


Figure 5: Isolation TX – RX.

9 Reflection coefficients







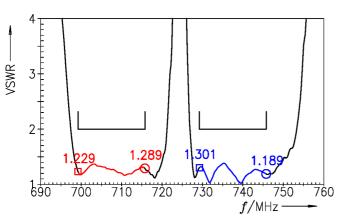
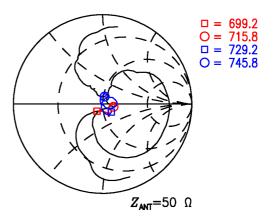


Figure 7: Reflection coefficient at ANT port.



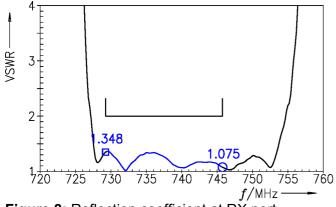
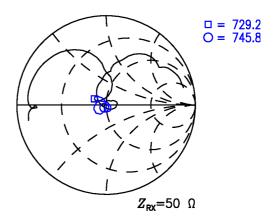


Figure 8: Reflection coefficient at RX port.





10 Packing material

10.1 Tape

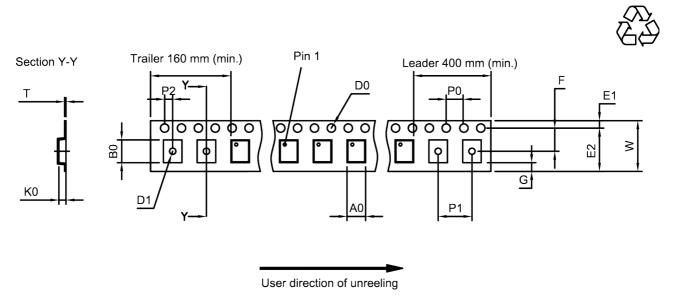


Figure 9: Drawing of tape (first-angle projection) for illustration only and not to scale. The valid tape dimensions are listed in Table 1.

A ₀	1.4±0.05 mm	E ₂	6.25 mm (min.)	P ₁	4.0±0.1 mm
B ₀	1.8±0.05 mm	F	3.5±0.05 mm	 P ₂	2.0±0.05 mm
D ₀	1.5+0.1/-0 mm	G	0.75 mm (min.)	Т	0.25±0.03 mm
D ₁	0.6+0.1/-0 mm	K ₀	0.7±0.05 mm	W	8.0+0.3/-0.1 mm
E ₁	1.75 _{±0.1} mm	P ₀	4.0±0.1 mm		

Table 1: Tape dimensions.



10.2 Reel with diameter of 180 mm

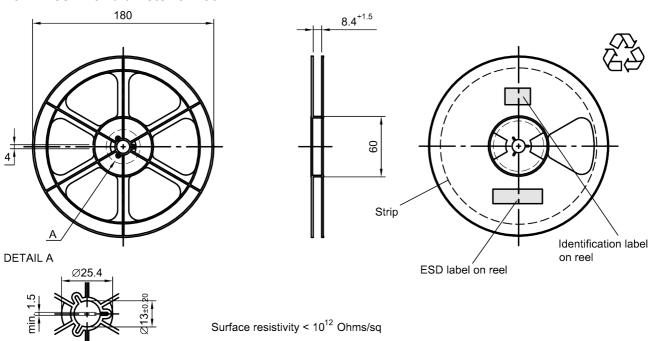


Figure 10: Drawing of reel (first-angle projection) with diameter of 180 mm.

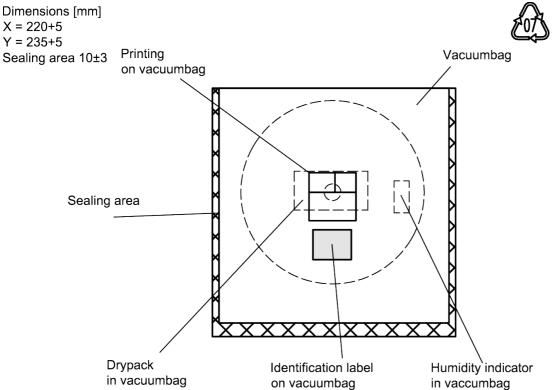


Figure 11: Drawing of moisture barrier bag (MBB) for reel with diameter of 180 mm.

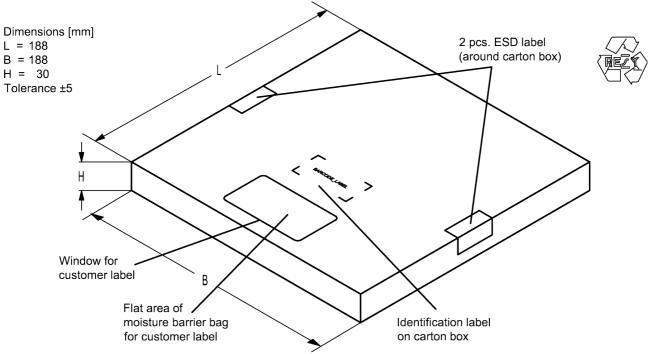


Figure 12: Drawing of folding box for reel with diameter of 180 mm.

10.3 Reel with diameter of 330 mm

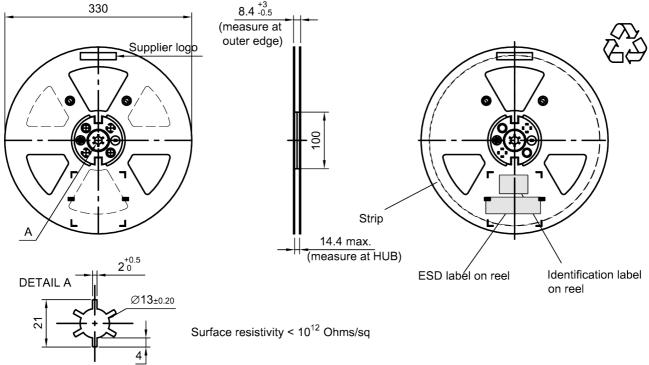


Figure 13: Drawing of reel (first-angle projection) with diameter of 330 mm.



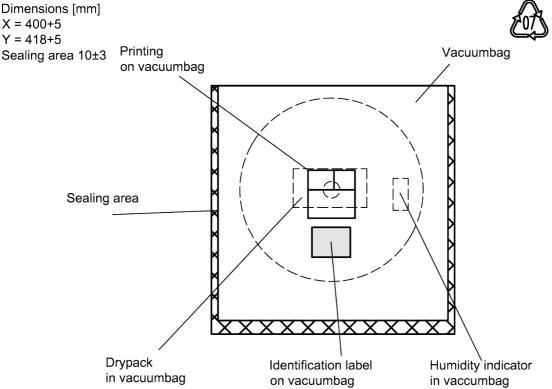


Figure 14: Drawing of moisture barrier bag (MBB) for reel with diameter of 330 mm.

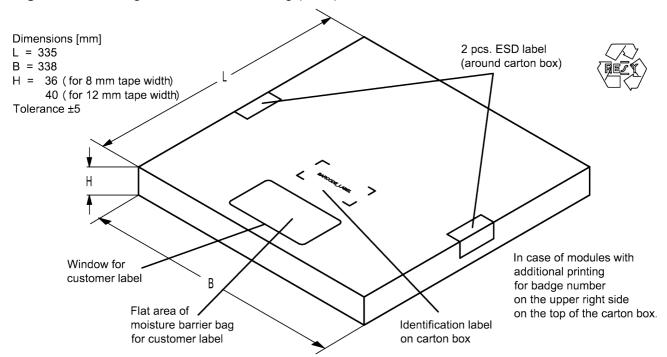


Figure 15: Drawing of folding box for reel with diameter of 330 mm.



11 Marking

Products are marked with product type number and lot number encoded according to Table 2:

■ Type number:

The 4 digit type number of the ordering code, e.g., B3xxxxB1234xxxx, is encoded by a special BASE32 code into a 3 digit marking.

Example of decoding type number marking on device in decimal code.

16J => 1234 1 x 32^2 + 6 x 32^1 + 18 (=J) x 32^0 = 1234

The BASE32 code for product type B1272 is 17R.

■ Lot number:

The last 5 digits of the lot number, e.g., are encoded based on a special BASE47 code into a 3 digit marking.

Example of decoding lot number marking on device in decimal code.

5UY => 12345 $5 \times 47^2 + 27 (=U) \times 47^1 + 31 (=Y) \times 47^0 =$ 12345

Adopted BASE32 code for type number						
Decimal	Base32	Decimal	Base32			
value	code	value	code			
0	0	16	G			
1	1	17	Н			
2	2	18	J			
3	3	19	K			
4	4	20	M			
5	5	21	N			
6	6	22	Р			
7	7	23	Q			
8	8	24	R			
9	9	25	S			
10	Α	26	Т			
11	В	27	V			
12	С	28	W			
13	D	29	Х			
14	E	30	Y			
15	F	31	Z			

Adopted BASE47 code for lot number					
Decimal	Base47	Decimal	Base47		
value	code	value	code		
0	0	24	R		
1	1	25	S		
2	2	26	Т		
3	3	27	U		
4	4	28	V		
5	5	29	W		
6	6	30	Х		
7	7	31	Y		
8	8	32	Z		
9	9	33	b		
10	Α	34	d		
11	В	35	f		
12	С	36	h		
13	D	37	n		
14	E	38	r		
15	F	39	t		
16	G	40	V		
17	Н	41	\		
18	J	42	?		
19	K	43	{		
20	L	44	}		
21	M	45	<		
22	N	46	>		
23	Р				

Table 2: Lists for encoding and decoding of marking.



12 Soldering profile

The recommended soldering process is in accordance with IEC $60068-2-58-3^{rd}$ edit and IPC/JEDEC J-STD-020B.

ramp rate	≤ 3 K/s
preheat	125 °C to 220 °C, 150 s to 210 s, 0.4 K/s to 1.0 K/s
T > 220 °C	30 s to 70 s
T > 230 °C	min. 10 s
T > 245 °C	max. 20 s
<i>T</i> ≥ 255 °C	_
peak temperature T_{peak}	250 °C +0/-5 °C
wetting temperature T_{\min}	230 °C +5/-0 °C for 10 s ± 1 s
cooling rate	≤ 3 K/s
soldering temperature <i>T</i>	measured at solder pads

Table 3: Characteristics of recommended soldering profile for lead-free solder (Sn95.5Ag3.8Cu0.7).

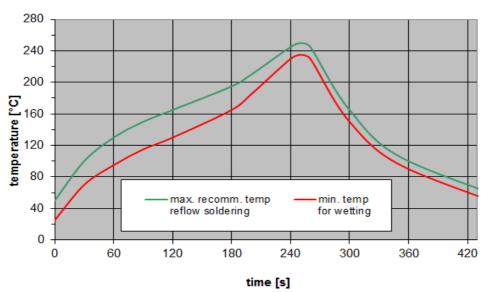


Figure 16: Recommended reflow profile for convection and infrared soldering – lead-free solder.



13 Annotations

13.1 RoHS compatibility

ROHS-compatible means that products are compatible with the requirements according to Art. 4 (substance restrictions) of Directive 2011/65/EU of the European Parliament and of the Council of June 8th, 2011, on the restriction of the use of certain hazardous substances in electrical and electronic equipment ("Directive") with due regard to the application of exemptions as per Annex III of the Directive in certain cases.

13.2 Scattering parameters (S-parameters)

The pin/port assignment is available in the headers of the S-parameter files. Please contact your local RF360 sales office.

13.3 Ordering codes and packing units

Ordering code	Packing unit
B39741B1272L210	15000 pcs
B39741B1272L210S 5	5000 pcs

Table 4: Ordering codes and packing units.



14 Cautions and warnings

14.1 Display of ordering codes for RF360 products

The ordering code for one and the same product can be represented differently in data sheets, data books, other publications and the website of RF360, or in order-related documents such as shipping notes, order confirmations and product labels. The varying representations of the ordering codes are due to different processes employed and do not affect the specifications of the respective products. Detailed information can be found on the Internet under https://rffe.gualcomm.com/.

14.2 Material information

Due to technical requirements components may contain dangerous substances. For information on the type in question please also contact one of our sales offices.

For information on recycling of tapes and reels please contact one of our sales offices.

14.3 Moldability

Before using in overmolding environment, please contact your local RF360 sales office.

14.4 Package information

Landing area

The printed circuit board (PCB) land pattern (landing area) shown is based on RF360 internal development and empirical data and illustrated for example purposes, only. As customers' SMD assembly processes may have a plenty of variants and influence factors which are not under control or knowledge of RF360, additional careful process development on customer side is necessary and strongly recommended in order to achieve best soldering results tailored to the particular customer needs.

Dimensions

Unless otherwise specified all dimensions are understood using unit millimeter (mm).

Projection method

Unless otherwise specified first-angle projection is applied.



15 Important notes

The following applies to all products named in this publication:

- 1. Some parts of this publication contain statements about the suitability of our products for certain areas of application. These statements are based on our knowledge of typical requirements that are often placed on our products in the areas of application concerned. We nevertheless expressly point out that such statements cannot be regarded as binding statements about the suitability of our products for a particular customer application. As a rule, RF360 Europe GmbH and its affiliates are either unfamiliar with individual customer applications or less familiar with them than the customers themselves. For these reasons, it is always ultimately incumbent on the customer to check and decide whether an RF360 product with the properties described in the product specification is suitable for use in a particular customer application.
- 2. We also point out that in individual cases, a malfunction of electronic components or failure before the end of their usual service life cannot be completely ruled out in the current state of the art, even if they are operated as specified. In customer applications requiring a very high level of operational safety and especially in customer applications in which the malfunction or failure of an electronic component could endanger human life or health (e.g. in accident prevention or life-saving systems), it must therefore be ensured by means of suitable design of the customer application or other action taken by the customer (e.g. installation of protective circuitry or redundancy) that no injury or damage is sustained by third parties in the event of malfunction or failure of an electronic component.
- 3. The warnings, cautions and product-specific notes must be observed.
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